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(54) HEAT-RESISTANT ADHESIVE MATERIAL

(57)Abstract:

PURPOSE: To obtain a heat-resistant adhesive material capable of bonding an adhesive at a low temperature, free from lowering of adhesiveness at high temperature, excellent in electric characteristics and chemical resistance, and further, remarkably improved in adhesion.
 CONSTITUTION: This heat-resistant adhesive material has a thermoplastic heat-resistant adhesive layer A on at least one side of a heat-resistant resin layer B and the thickness of the thermoplastic heat-resistant adhesive layer A is $\geq 0.1\mu\text{m}$ and $\leq 15\mu\text{m}$ and modulus (at 250°C) of the thermoplastic heat-resistant adhesive layer A is $\geq 106\text{dyn/cm}^2$ and $< 10\text{dyn/cm}^2$.

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